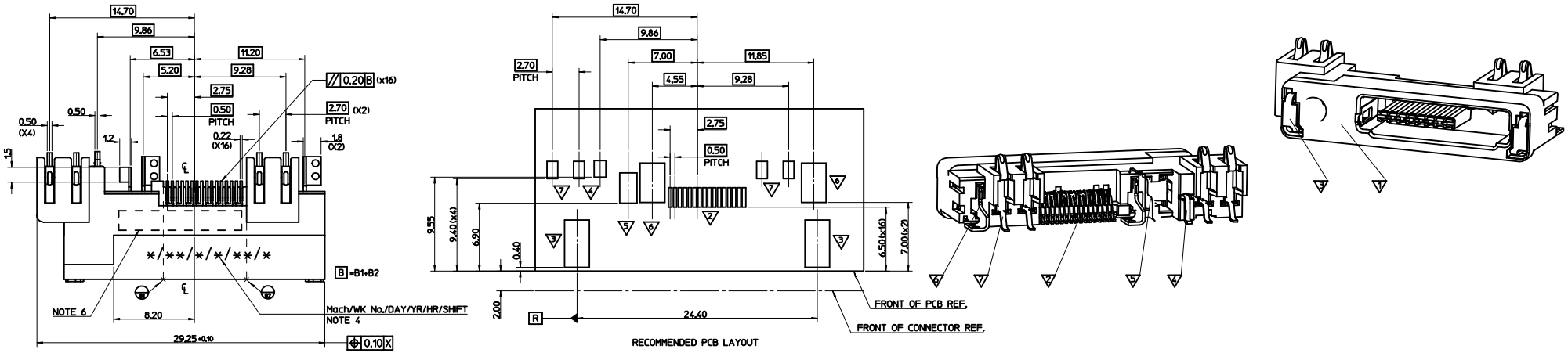
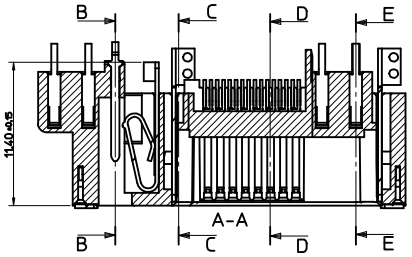
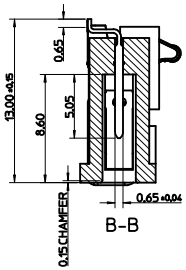
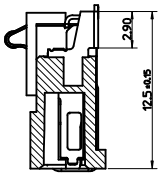
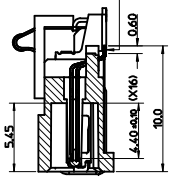
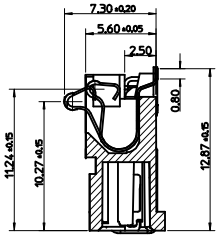




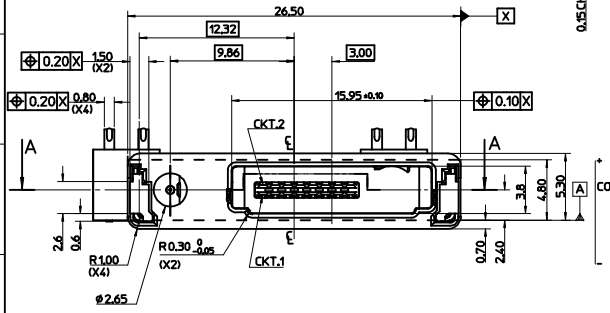


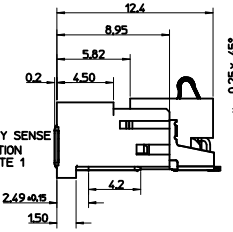


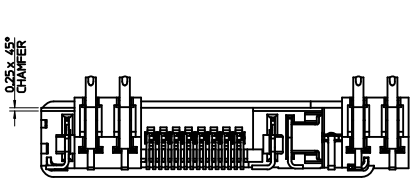




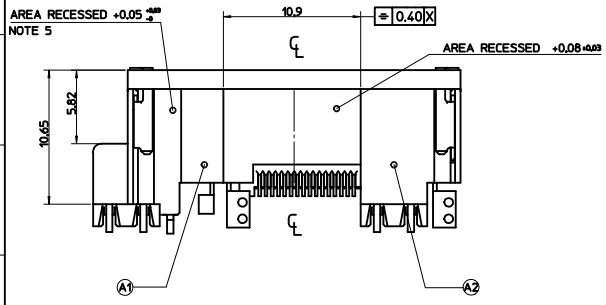
	COMPONENT	RECOMMENDED PCB PAD DIMENSION	POSITION	QTY
V7	SIGNAL CONTACT	0.35 +0.05/-0 X 2.0 (x16) ⊕0.10R	⊕0.10X	16
V7	CHARGER PADS	2.50 X 4.8 (x2) ⊕0.10R	⊕0.30X	2
V7	DC PIN	1.20 X 1.7 (x1) ⊕0.10R	⊕0.30X	1
V7	DC BEAM	1.75 X 3.1 (x1) ⊕0.10R	⊕0.30X	1
V7	LOCKING LATCHES	2.50 X 4.0 (x2) ⊕0.10R	⊕0.30X	2
V7	BATTERY CONTACT	1.10 X 1.8 (x4) ⊕0.10R	⊕0.30X	4







	COMPONENT	DESCRIPTION	QTY
V7	HOUSING	45% GLASS FILLED NYLON 46 (RATED UL94 V-0), COLOUR BLACK.	1
V7	SIGNAL CONTACT	MATERIAL: 0.20 REF. THK. PHOSPHOR BRONZE. PLATING: 1.27um MIN. NICKEL UNDERCOAT ALL OVER. 0.1um MIN. GOLD OVER 1.0um MIN. PALLADIUM NICKEL ON CONTACT AREA. 3.0um MIN. TIN IN SOLDER TAIL AREA (ALL SIDES).	16
V7	CHARGER PADS/ SMT RETENTION NAILS	MATERIAL: 0.30 REF. THK. PHOSPHOR BRONZE. PLATING: 1.27um MIN. NICKEL UNDERCOAT OVERALL. 0.1um MIN. GOLD FLASH OVER 1.0um MIN. PALLADIUM NICKEL IN CONTACT AREA. 3.0um MIN. Sn IN SOLDER TAIL AREA (ALL SIDES).	2
V7	DC PIN	MATERIAL: 0.65 REF. THK. COPPER ALLOY PLATING: 1.27um MIN. NICKEL UNDERCOAT ALL OVER. 3-4um NICKEL IN CONTACT AREA. 3.0um MIN. TIN IN SOLDER TAIL AREA.	1
V7	DC BEAM	MATERIAL: 0.28 REF. THK. BERYLLIUM COPPER. PLATING: 0.25um MIN. NICKEL UNDERCOAT ALL OVER. 2-3um NICKEL UNDER 3um MIN SILVER, ONE SIDE ONLY 3.0um MIN. TIN IN SOLDER TAIL AREA (ALL SIDES).	1
V7	LOCKING LATCHES	MATERIAL: 0.30 REF. THK. STAINLESS STEEL. PLATING: 3-5um TIN OVER 1.27 -2.50um NICKEL UNDERCOAT ALL OVER.	2
V7	BATTERY CONTACT	MATERIAL: 0.17 REF. THK. PHOSPHOR BRONZE. PLATING: 1.27um MIN. NICKEL UNDERCOAT OVERALL. 0.10um MIN. GOLD FLASH OVER PALLADIUM-NICKEL (80/20) 1.0-1.5um ON CONTACT AREA. 3.0um MIN. Sn IN SOLDER TAIL AREA.	4



NOTES:

1. COPLANARITY: ALL SMT TAILS TO LIE WITHIN A COPLANARITY BAND OF -0.05 TO -0.15 FROM DATUM 'A'. SEE COPLANARITY SENSE DIRECTION.
   DATUM 'A' IS TO BE TAKEN AS THE PLANE OF A METAL BLOCK ON WHICH DATUM A1 & A2 REST.
2. PACKAGING: TAPE AND REEL. SEE DRAWING SD-91403-005
3. LEAD FLATNESS: 0.1 FOR ALL SMT TAILS
4. TEXT TO BE LASER PRINTED
5. GATING VESTIGE MARK NOT TO PROTRUDE PAST DATUM A
6. TEXT: PART NO./ MX I.D./ CAVITY I.D., TO BE 1.0 HIGH AND RAISED 0.1 MAX

REMOVE LEAD FROM PLATING
EC NO: E2004-0574
DRWN: DCARTON 04.02.26
CHK:
APPR:
DESCRIPTION
REV
N

QUALITY SYMBOLS
MAJOR
CRITICAL

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±---	±---
3 PLACES	±---	±---
2 PLACES	±0.05	±---
1 PLACE	±0.10	±---
ANGULAR:	± 1/2°	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 5:1
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY
SHT REV
REVISE ON CAD ONLY

DRAWN BY & DATE dcarton 00.07.19
CHECKED BY & DATE jhorgan 99.08.10
APPROVED BY & DATE mwhite 99.08.10
CAD FILENAME

TITLE: MOBILE PHONE I/O CONNECTOR

MOLEX INCORPORATED

MATERIAL NO. 91403-0001
DRAWING NO. SD-91403-001
SHEET NO. 1 of 1
SIZE D